



(2,54 mm) .100"

HLE SERIES

COST-EFFECTIVE RELIABLE SOCKET

Mates With:
 TSW, MTSW, DW,
 EW, ZW, TLW, TSM,
 MTLW, HW

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?HLE

Insulator Material:
 Black Liquid Crystal Polymer
Contact Material:
 BeCu
Plating:
 Au or Sn over
 50µ" (1,27 µm) Ni
Current Rating (HLE/TSM):
 4.1 A per pin
 (1 pin powered per row)
Voltage Rating:
 400 VAC
Operating Temp Range:
 -55°C to +125°C
Insertion Depth:
 (1,78 mm) .070" to
 (3,43 mm) .135", pass-through,
 or (2,59 mm) .102" min
 plus board thickness for
 bottom entry
Insertion Force:
 (Single contact only)
 2 oz (0,56 N) avg.
Withdrawal Force:
 (Single contact only)
 1.6 oz (0,44 N) avg.
RoHS Compliant:
 Yes

Processing:
Lead-Free Solderable:
 Yes
SMT Lead Coplanarity:
 (0,10 mm) .004" max (02-20)
 (0,15 mm) .006" max (21-50)

RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality



ALSO AVAILABLE (MOQ Required)

- Other platings
- Contact Samtec.

Note: Some lengths, styles and options are non-standard, non-returnable.

HLE	1	NO. PINS PER ROW	02	PLATING OPTION	DV	TAIL OPTION	OTHER OPTION
02 thru 50				-F = Gold flash on contact, Matte Tin on tail	Leave blank for Surface Mount		-BE = Bottom Entry (N/A with -TE)
				-L = 10µ" (0,25 µm) Gold on contact, Matte Tin on tail			
				<p>(Requires -BE for Bottom Entry)</p>		-A = Alignment Pin (4 positions min.) Metal or plastic at Samtec discretion (N/A with -TE, -PE & -LC)	
						-TE = Through-Hole Top Entry	-LC = Locking Clip (2 positions min.) (N/A with -A) (Manual placement required)
						-K = (6,50 mm) .256" DIA Polyimide Film Pick & Place Pad (3 positions min.) Not available with -TE or -PE tail option	
						-PE = Through-hole Pass-Through Entry	-P = Metal Pick & Place Pad (3 positions min.)
				<p>(Requires -BE for Bottom Entry)</p>		-TR = Tape & Reel Packaging (29 positions max.)	